

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00153	0.51	0.09129
	Doped silicon	Silicon (Si)	7440-21-3	0.29844	99.49	17.80871
		<b>Subtotal</b>		<b>0.29997</b>	<b>100</b>	<b>17.9</b>
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.36868	100.0	22
		<b>Subtotal</b>		<b>0.36868</b>	<b>100</b>	<b>22</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02006	0.03	1.197
	Copper alloy	Iron (Fe)	7439-89-6	0.06686	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.77749	99.87	3,984.813
		<b>Subtotal</b>		<b>66.86441</b>	<b>100</b>	<b>NaN</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.08377	6.5	124.345
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.12929	16.0	306.08
	Filler	Silica fused	60676-86-0	22.76122	71.0	1,358.23
	Flame retardant	Metal hydroxide		2.08377	6.5	124.345
		<b>Subtotal</b>		<b>32.05805</b>	<b>100</b>	<b>NaN</b>
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01173	5.0	0.7
	Lead alloy	Silver (Ag)	7440-22-4	0.00587	2.5	0.35
	Lead alloy	Lead (Pb)	7439-92-1	0.21702	92.5	12.95
		<b>Subtotal</b>		<b>0.23462</b>	<b>100</b>	<b>14</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.17428	100.0	10.4
		<b>Subtotal</b>		<b>0.17428</b>	<b>100</b>	<b>10.4</b>
		<b>Total</b>		<b>100.00001</b>	<b>100</b>	<b>NaN</b>

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